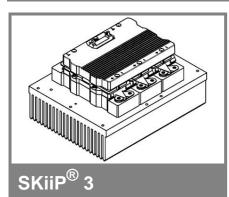
## SKiiP 1513GB122-3DL



2-pack-integrated intelligent Power System

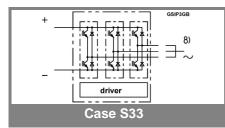
#### **Power Section**

SKiiP 1513GB122-3DL

Preliminary Data

#### Features

- SKiiP technology inside
- SPT (Soft Punch Trough) IGBTs
- CAL diode technology
- Integrated current sensor
- Integrated temperature sensor
- Integrated heat sink
- IEC 60721-3-3 (humidity) class 3K3/IE32 (SKiiP<sup>®</sup> 3 System)
- IEC 68T.1 (climate) 40/125/56 (SKiiP<sup>®</sup> 3 power section)
- UL recognized File no. E63532 (SKiiP<sup>®</sup> 3 power section)
- with assembly of suitable MKP capacitor per terminal (SEMIKRON type is recommended)
- AC connection busbars must be connected by the user; copper busbars available on request



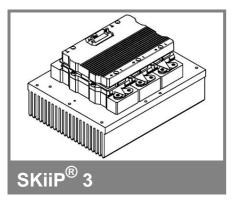
Absolute	e Maximum Ratings	$_{\rm s}$ = 25 °C unless otherwise specified							
Symbol Conditions		Values	Units						
IGBT									
V <sub>CES</sub> V <sub>CC</sub> <sup>1)</sup>		1200	V						
	Operating DC link voltage	900	V						
V <sub>GES</sub>		± 20	V						
I <sub>C</sub>	T <sub>s</sub> = 25 (70) °C	1500 (1125)	А						
Inverse o	Inverse diode								
I <sub>F</sub> = - I <sub>C</sub>	T <sub>s</sub> = 25 (70) °C	1340 (1020)	А						
I <sub>FSM</sub>	T <sub>j</sub> = 150 °C, t <sub>p</sub> = 10 ms; sin	12960	А						
I²t (Diode)	Diode, T <sub>j</sub> = 150 °C, 10 ms	840	kA²s						
T <sub>j</sub> , (T <sub>stg</sub> )		- 40 + 150 (125)	°C						
V <sub>isol</sub>	rms, AC, 1 min, main terminals to heat sink	3000	V						
I <sub>AC-terminal</sub>	per AC terminal, rms, T <sub>s</sub> = 70 °C,	400	А						
	T <sub>terminal</sub> <115 °C								

<b>Characteristics</b> $T_s = 25 \text{ °C}$ unless otherwise spe							
Symbol	Symbol Conditions		typ.	max.	Units		
IGBT							
V <sub>CEsat</sub>	$I_{C}$ = 900 A, $T_{j}$ = 25 (125) °C; measured at terminal		2,3 (2,5)	2,6	V		
V <sub>CEO</sub>	T <sub>i</sub> = 25 (125) °C; at terminal		1,1 (1)	1,3 (1,2)	V		
r <sub>CE</sub>	T <sub>j</sub> = 25 (125) °C; at terminal		1,3 (1,7)	1,5 (1,9)	mΩ		
I <sub>CES</sub>	V <sub>GE</sub> = 0 V, V <sub>CE</sub> = V <sub>CES</sub> , T <sub>i</sub> = 25 (125) °C		3,6 (108)		mA		
E <sub>on</sub> + E <sub>off</sub>	$I_{\rm C}$ = 900 A, V <sub>CC</sub> = 600 V		270		mJ		
	T <sub>i</sub> = 125 °C, V <sub>CC</sub> = 900 V		476		mJ		
R <sub>CC+EE</sub>	terminal chip, T <sub>i</sub> = 25 °C		0,17		mΩ		
L <sub>CE</sub>	top, bottom		4		nH		
C <sub>CHC</sub>	per phase, AC-side		5,1		nF		
Inverse	diode				•		
$V_F = V_{EC}$	I <sub>F</sub> = 900 A, T <sub>j</sub> = 25 (125) °C measured at terminal		1,8 (1,5)	2,3	V		
V <sub>TO</sub>	T <sub>i</sub> = 25 (125) °C		1 (0,7)	1,2 (0,9)	V		
r <sub>T</sub>	T <sub>i</sub> = 25 (125) °C		0,9 (0,9)	1,2 (1,2)	mΩ		
E <sub>rr</sub>	$I_{\rm C}$ = 900 A, $V_{\rm CC}$ = 600 V		72		mJ		
	$T_{j}$ = 125 °C, $V_{CC}$ = 900 V		92		mJ		
Mechan	ical data						
M <sub>dc</sub>	DC terminals, SI Units	6		8	Nm		
М <sub>ас</sub>	AC terminals, SI Units	13		15	Nm		
W	SKiiP <sup>®</sup> 3 System w/o heat sink		2,4		kg		
W	heat sink		7,5		kg		
Thermal characteristics (PX 16 heat sink with fan SKF 16B-230-1); "s" reference to heat sink; "r" reference to built-in temperature sensor (acc. IEC 60747-15)							
R <sub>th(j-s)l</sub>	per IGBT			0,02	K/W		
R <sub>th(i-s)D</sub>	per diode			0,038	K/W		

R <sub>th(j-s)I</sub>	per IGB	Г					0,02	K/W	
R <sub>th(j-s)D</sub>	per diod	per diode				0,038			
Z <sub>th</sub>	R <sub>i</sub> (mK/V	R <sub>i</sub> (mK/W) (max. values)			tau <sub>i</sub> (s)				
	1	2	3	4	1	2	3	4	
Z <sub>th(j-r)I</sub>	3,4	9,6	7	0	363	0,18	0,04	1	
Z <sub>th(j-r)D</sub>	12	12	18	20	30	5	0,25	0,04	
Z <sub>th(r-a)</sub>	2,1	20	5,5	1,4	210	85	11	0,4	

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# SKiiP 1513GB122-3DL



### 2-pack-integrated intelligent Power System

2-pack integrated gate driver SKiiP 1513GB122-3DL

Preliminary Data

### Gate driver features

- CMOS compatible inputs
- Wide range power supply
- Integrated circuitry to sense phase current, heat sink temperature and DC-bus voltage (option)
- Short circuit protection
- Over current protection
- Over voltage protection (option)
- Power supply protection against under voltage
- Interlock of top/bottom switch
- · Isolation by transformers
- Fibre optic interface (option for GB-types only)
- IEC 68T.1 (climate) 40/85/56 (SKiiP<sup>®</sup> 3 gate driver)

Absolute Maximum Ratings						
Symbol	Conditions	Values	Units			
V <sub>S2</sub>	unstabilized 24 V power supply	30	V			
V <sub>i</sub>	input signal voltage (high)	15 + 0,3	V			
dv/dt	secondary to primary side	75	kV/μs			
V <sub>isollO</sub>	input / output (AC, rms, 2)	3000	V			
VisoIPD	partial discharge extinction voltage, rms, $Q_{PD} \leq 10 \text{ pC}$ ;	1170	V			
V <sub>isol12</sub>	output 1 / output 2 (AC, rms, 2 s)	1500	V			
f	switching frequency	10	kHz			
T <sub>op</sub> (T <sub>stg</sub> )	operating / storage temperature	- 40 + 85	°C			

Characte	ristics	(T <sub>a</sub>			= 25 °C)
Symbol	Conditions	min.	typ.	max.	Units
V <sub>S2</sub>	supply voltage non stabilized	13	24	30	V
I <sub>S2</sub>	V <sub>S2</sub> = 24 V	278+29*f/	278+29*f/kHz+0,00015*(I <sub>AC</sub> /A) <sup>2</sup>		
V <sub>iT+</sub>	input threshold voltage (High)	11,2			V
V <sub>iT-</sub>	input threshold voltage (Low)			5,4	V
R <sub>IN</sub>	input resistance		10		kΩ
C <sub>IN</sub>	input capacitance		1		nF
t <sub>d(on)IO</sub>	input-output turn-on propagation time		1,3		μs
t <sub>d(off)IO</sub>	input-output turn-off propagation time		1,3		μs
t <sub>pERRRESET</sub>	error memory reset time		9		μs
t <sub>TD</sub>	top / bottom switch interlock time		3,3		μs
I <sub>analogOUT</sub>	max. 5mA; 8 V corresponds to 15 V supply voltage for external components		1500		A
I <sub>s1out</sub>	max. load current			50	mA
I <sub>TRIPSC</sub>	over current trip level				
	$(I_{analog} OUT = 10 V)$		1875		А
T <sub>tp</sub>	over temperature protection	110		120	°C
U <sub>DCTRIP</sub>	U <sub>DC</sub> -protection ( U <sub>analog OUT</sub> = 9 V);	i	not mplemente	d	V
	(option for GB types)				

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